MIRTEC to Exhibit Complete Line of Technologically Advanced
3D AOI and SPI Inspection Systems at IPC APEX 2016

February 2016 – MIRTEC, “The Global Leader in Inspection Technology,” will premier its complete line of 3D AOI and SPI Inspection Systems in Booth #1334 at the 2016 IPC APEX EXPO. The premier technical conference and exhibition for the electronics manufacturing industry will take place March 15-17, 2016 at the Las Vegas Convention Center.

“We are very excited about the products that we will be presenting at APEX 2016,” stated Brian D’Amico, President of MIRTEC’s North American Sales and Service Division. “MIRTEC will feature a total of seven inspection systems specifically designed to address the full spectrum of inspection requirements associated with the electronics manufacturing industry.”

The award-winning MV-6 OMNI 3D AOI Machine is configured with MIRTEC’s exclusive OMNI-VISION® 3D Inspection Technology which combines our 15 Mega Pixel CoaXPress Camera Technology with MIRTEC’s revolutionary Digital Multi-Frequency Quad Moiré 3D system in a newly designed cost-effective platform. MIRTEC’s 15 Mega Pixel CoaXPress Vision System is a proprietary camera system designed and manufactured by MIRTEC for use with our complete product range of 3D inspection systems. MIRTEC’s Digital Multi-Frequency Quad Moiré Technology, provides true 3D inspection using a total of four (4) Programmable Digital Moiré Projectors to yield precise height measurement data used to detect lifted component and lifted lead defects as well as solder volume post reflow. Fully configured the new MIRTEC MV-6 OMNI machines feature four (4) 10 Mega Pixel Side-View Cameras in addition to the 15 Mega Pixel Top-Down Camera. There is little doubt that this new technology has set the standard by which all other inspection equipment is measured. MIRTEC will have two (2) MV-6 OMNI’s on display one configured with a 10um lens for High-Performance applications and the other with a 15um lens for High-Speed applications.

MIRTEC’s MS-11E 3D SPI Machine is configured with MIRTEC’s exclusive 15MP CoaXPress Vision System, providing enhanced image quality, superior accuracy and incredibly fast inspection rates.

The machine uses Dual Projection Shadow Free Moiré Phase Shift Imaging Technology to inspect solder paste depositions on PCBs post screen print for insufficient solder, excessive solder, shape deformity, shift of deposition and bridging. The MS-11e uses the same robust platform as MIRTEC’s MV-6 OMNI Series.

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MIRTEC’s **MV-7 OMNI-QHD 3D AOI Machine** features the next generation of MIRTEC’s award-winning OMNI-VISION® 3D Inspection Technology in a High-Performance AC Servo Drive Platform. This revolutionary technology combines our proprietary 15MP CoaXPress Vision System with MIRTEC’s exclusive Quantum High Definition (2048x1536) Digital Multi-Frequency 3D Projection Technology to provide unprecedented image quality, accuracy and repeatability necessary for precision inspection of SMT devices on finished PCB assemblies. This new technology will, undoubtedly, set the standard by which all other 3D inspection equipment will be measured. The MV-7 OMNI-QHD machine also features four (4) 10 Mega Pixel Side-View Cameras for inspection of Regions of Interest which are not accessible with the 15 MP Top-Down Camera.

MIRTEC’s **MV-6E In-Line AOI Machine** combines our exclusive 10 Mega Pixel Top-Down camera with a Precision 13.4um Telecentric Compound Lens and four (4) 10 Mega Pixel Side-View Cameras in a newly designed cost effective platform. The MV-6e is also configured with MIRTEC’s exclusive **INTELLI-SCAN® 3D Laser System**, providing superior lifted lead detection for gull wing devices and four-point height measurement capability for co-planarity testing of BGA and CSP devices.

The **MV-3L Desktop AOI Machine** is the industry’s most widely accepted five (5) camera desktop AOI system. This system is configured with one Top-Down View 10 Mega Pixel camera with a Precision 13.4um Telecentric Compound Lens and four (4) 10 Mega Pixel Side-View Cameras. It also features our exclusive **INTELLI-BEAM® 3D Laser System**. This advanced technology provides: four-point height measurement capability for co-planarity testing of BGA and CSP devices as well as enhanced solder paste measurement capability.

MIRTEC’s total quality management system software, **INTELLISYS®** also will be on display at the IPC APEX EXPO. This software suite promotes continuous process improvement by allowing manufacturers to track and eliminate defects on inspected assemblies.

“MIRTEC has earned a solid reputation in the industry by providing unprecedented performance, quality and cost-effectiveness to the inspection environment,” continued D’Amico. “We look forward to welcoming visitors to our booth #1334 during the three-day event.”

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MIRTEC is a leading global supplier of automated inspection systems to the electronics manufacturing industry. For further information, please visit [www.mirtec.com](http://www.mirtec.com)